

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
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EPAS ID: PAT5028495

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	CHEN-PING WANG	06/08/2018
RECEIVING PARTY DATA		
Name:	GETAC TECHNOLOGY CORPORATION	
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State/Country:	TAIWAN	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	16017984
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DATE SIGNED:	06/28/2018	
Total Attachments: 1		
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ASSIGNMENT

Whereas, I/we, Chen-Ping WANG, hereafter referred to as "Assignor(s)," have invented certain new and useful improvements as set forth in the below identified application for United States Letters Patent:

Title: **ENHANCED HEAT DISSIPATION MODULE, COOLING FIN STRUTURE AND STAMPING METHOD THEREOF**

☐ for which an application for a United States Patent was filed on _____ Application Number _____;

☐ for which an application for a United States Patent was executed on [_____]; and

Whereas, Getac Technology Corporation of Hsinchu County, Taiwan, herein referred to as "Assignee," whose mailing address is 4F, No.1, R&D Road 2, Hsinchu Science-Based Industrial Park., is desirous of acquiring the entire right, title and interest in said invention and application and any U.S. Letters Patent which may be granted on the same;

Now, therefore, to all whom it may concern, be it known that for good and valuable consideration, the receipt whereof is hereby acknowledged, I/we, the Assignor(s), by these presents do sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States and the entire right, title and interest in and to any and all Patents which may be granted therefore in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor(s) had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor(s) further agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application, execute, verify, acknowledge and deliver all such further papers and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

In testimony whereof, Assignor(s) have signed his/her/their name(s) on the date(s) indicated.

Chen-Ping Wang
Chen-Ping WANG

June 8, 2018

Date